2SA0885 (2SA885)

Silicon PNP epitaxial planar type

For low-frequency power amplification Complementary to 2SC1846

■ Features

- Output of 3 W can be obtained by a complementary pair with 2SC1846
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-45	V
Collector to emitter voltage	V_{CEO}	-35	V
Emitter to base voltage	V_{EBO}	-5	V
Peak collector current	I_{CP}	-1.5	A
Collector current	I_{C}	-1	A
Collector power dissipation	P_{C}	1.2 *1	W
		5 *2	
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C



^{*2:} With a $100 \times 100 \times 2$ mm A1 heat sink

Unit: mm 8.0^{+0.5} 9.3.16±0.1 0.75±0.1 0.5±0.1 1: Emitter 2: Collector 3: Base TO-126B-A1 Package

■ Electrical Characteristics $T_C = 25$ °C

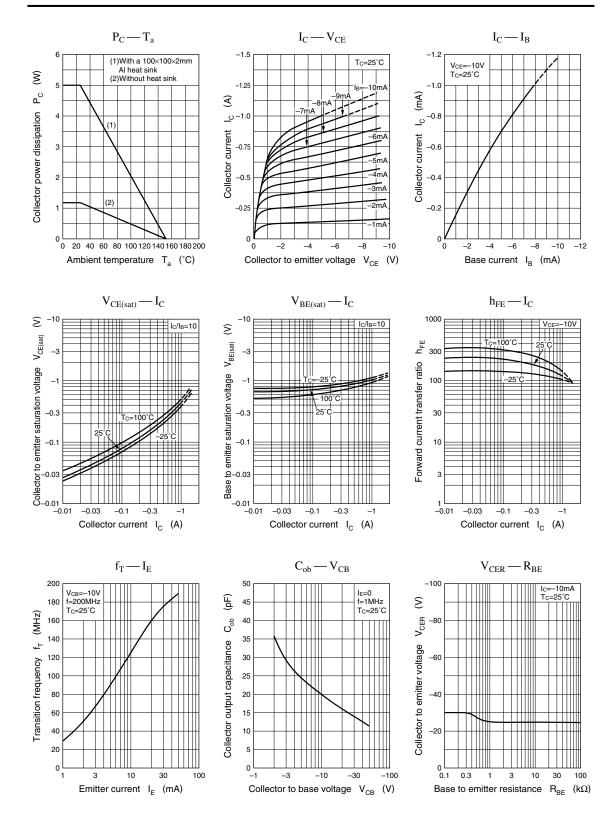
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ
	I_{CEO}	$V_{CE} = -20 \text{ V}, I_{B} = 0$			-100	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = -5V, I_C = 0$			-10	μΑ
Collector to base voltage	V _{CBO}	$I_C = -10 \mu\text{A}, I_E = 0$	-45			V
Collector to emitter voltage	V_{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-35			V
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -10 \text{ V}, I_{C} = -500 \text{ mA}$	85		340	
	h _{FE2}	$V_{CE} = -5 \text{ V}, I_{C} = -1 \text{ A}$	50			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$			- 0.5	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20	30	pF

Note) *: Rank classification

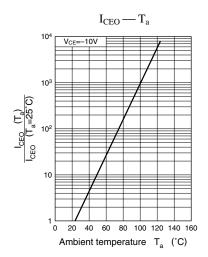
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h _{FE1}		85 to 170	120 to 240	170 to 340

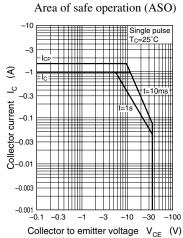
Note.) The Part number in the Parenthesis shows conventional part number.

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